A network of design centers boosting and initiating synergies between Innovative companies, industrial CPS-platforms and CPS-competency providers

Road2CPS – concertation event
January 30, 2017 - Bruxelles
EuroCPS in a nutshell

• Call: ICT-01-2014
• Launched: Feb 1\textsuperscript{st}, 2015
• Duration: 3 years

• 9 Countries
• 15 Partners
• 8 Technology Platforms

• Budget: 9,178,641€
• EC funding: 8,186,835€

浓缩

Industrial Experiment support: 76% of the EuroCPS funding
EuroCPS objectives

Innovative embedded ICT users across regions: Industrial experiments

Objective 1: Bring innovative CPS to businesses from any sectors

Objective 2: linking user-supplier across value-chains and regions

Outcome: Innovative EU CPS products + Sustained demand for EU manufacturing

Supported, manage and monitor by cascade funding partners
EuroCPS principle

3 open calls timed every 6 months (Last call closed in June)
- IE evaluated on their excellence, quality and impact
- IE (6-18 months) outcome targeted: 5 < TRL < 7
EuroCPS Industrial Experiments

- **SW intensive project**
  - USER (SW intensive project)
  - CPS specifications
  - HW
  - HW/SW integration
  - CPS platforms
  - SW prototype demonstrator

- **System integration project**
  - USER (System integration project)
  - CPS specifications
  - HW
  - HW/SW integration
  - CPS platforms
  - Comp. platforms
  - Integrated system prototype demonstrator

- **CPS w/ innovative component project**
  - USER (Innovative device project)
  - CPS specifications
  - HW
  - HW/SW integration
  - CPS platforms
  - Comp. platforms
  - System architecture virtual prototype demonstrator

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The 8 EuroCPS platforms

Software

Avionics Platform
Processing board & real time SW solutions provided by Thales

Integrated and Open Development Platform
Simulation methods and tools for development provided by AVL

Connectivity Platform
Solution for digitalization application provided by Schneider

STM32 Microcontroller Platform
32-bit product range provided by STMicroelectronics

iNEMO Inertial Platform
A sensor platform provided by STMicroelectronics

Quark System on Chip Platform
Low-power platform provided by Intel

Integration system

Power management Platform
Component platform provided by Infineon

Silicon Process and Package Technology
Leading-edge silicon processes and package technologies provided by STMicroelectronics

Hardware
EuroCPS SME financial support

Cascade funding (70% of the budget): Support R&D work of 3rd parties
+ Platform funding: Support the technology access
+ Competence funding: Support the expertise, know-how access
EuroCPS 1st, 2nd and 3rd open calls IEs

- 118 proposals
- 34 selected IEs

- 11 granted countries
- 2 not represented by the consortium
- <75% IE – cross border collaboration
EuroCPS 1st, 2nd and 3rd open calls IEs

Project type
Balanced IE repartitions among platform and competence partners

Application domains
- Smart factory 25%
- Smart agriculture 17%
- Smart cities 21%
- IoT protocol 4%
- Smart health 8%
- Smart mobility 25%
Thank you

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